

NEL-SYSTEM

**Wafer protection
tape remover**



HR8500III

TW-UV

**OPERATION
MANUAL**

**NITTO DENKO
NITTO SEIKI**

Overview

	 WARNING
	<p>Read this instruction manual carefully and have a complete understanding of the contents before use.</p> <p>Observe all warnings and cautions in this manual.</p> <p>Failures to observe warnings and cautions could cause of serious injuries to human body and damage/performance decrement of the equipment.</p> <p>Keep this instruction manual so that you can use it at anytime.</p>

This manual consists of below:

- Vol. 1 Installation manual
- Vol. 2 Operation manual
- Vol. 3 Maintenance manual

This manual is Vol. 2 Operation manual to operate the equipment correctly and safely by the operators.

The operators must follow the rules.

- The operators are allowed to do works shown in "Vol.2 Operation manual".
- Only authorized persons are allowed to do the works shown in "Vol. 1 Installation manual" and "Vol.3 Maintenance manual".
- The operators are not allowed to have use of any tools, such as screwdrivers and wrenches.
- The operators are not allowed to have keys for lockout and override the safety interlock.

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